

N/C

VS-15ETH06S-M3

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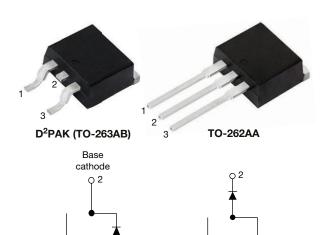
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COMPLIANT

HALOGEN

FREE

Hyperfast Rectifier, 15 A FRED Pt®



PRIMARY CHARACTERISTICS						
I _{F(AV)}	15 A					
V_{R}	600 V					
V _F at I _F	1.3 V					
t _{rr} (typ.)	22 ns					
T _J max.	175 °C					
Package	D ² PAK (TO-263AB), TO-262AA					
Circuit configuration	Single					

N/C

Anode

VS-15ETH06-1-M3

FEATURES

- · Hyperfast recovery time
- · Low forward voltage drop
- · Low leakage current
- 175 °C operating junction temperature
- Single die center tap module
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

DESCRIPTION / APPLICATIONS

State of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC boost stage in the AC/DC section of SMPS, inverters or as freewheeling diodes.

The extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS							
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS			
Peak repetitive reverse voltage	V_{RRM}		600	V			
Average rectified forward current	I _{F(AV)}	T _C = 140 °C	15				
Non-repetitive peak surge current	I _{FSM}	T _J = 25 °C	120	Α			
Peak repetitive forward current	I _{FM}		30				
Operating junction and storage temperatures	T _J , T _{Stg}		-65 to +175	°C			

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)							
PARAMETER SYMBOL TEST COND		TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Breakdown voltage, blocking voltage	V_{BR} , V_{R}	I _R = 100 μA	600	-	-	.,	
Farmend wells as	V	I _F = 15 A	=	1.8	2.2	V	
Forward voltage	V _F	I _F = 15 A, T _J = 150 °C	-	1.3	1.6		
Reverse leakage current	1-	$V_R = V_R$ rated	-	0.2	50	μA	
neverse leakage current	I _R	$T_J = 150 ^{\circ}\text{C}, V_R = V_R \text{rated}$	-	30	500	μΑ	
Junction capacitance	C _T	V _R = 600 V	-	20	-	pF	
Series inductance	L _S	Measured lead to lead 5 mm from package body	=	8.0	-	nH	



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DYNAMIC RECOVERY CHARACTERISTICS (T _C = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS	
Reverse recovery time		$I_F = 1 A$, $dI_F/dt = 1$	00 A/μs, V _R = 30 V	-	22	30		
		$I_F = 15 A$, $dI_F/dt = 10$	100 A/μs, V _R = 30 V	-	28	35	no	
	t _{rr}	T _J = 25 °C		-	29	-	ns ns	
		T _J = 125 °C	I _F = 15 A dI _F /dt = 200 A/μs V _R = 390 V	-	75	-		
Dools recovery oursent	I _{RRM}	T _J = 25 °C		-	3.5	-	- A - μC	
Peak recovery current		T _J = 125 °C		-	7	-		
Deverse vegevent shores	Q _{rr}	T _J = 25 °C		-	57	-		
Reverse recovery charge		T _J = 125 °C		-	300	-		
Reverse recovery time	t _{rr}		I _F = 15 A	-	51	-	ns	
Peak recovery current	I _{RRM}	T _J = 125 °C	$dI_F/dt = 800 A/\mu s$	-	20	-	Α	
Reverse recovery charge	Q _{rr}		V _R = 390 V	-	580	-	nC	

THERMAL - MECHANIC	THERMAL - MECHANICAL SPECIFICATIONS							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS		
Maximum junction and storage temperature range	T _J , T _{Stg}		-65	-	175	°C		
Thermal resistance, junction to case per leg	R _{thJC}		-	1.0	1.3			
Thermal resistance, junction to ambient per leg	R _{thJA}	Typical socket mount	-	-	70	°C/W		
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth, and greased	-	0.5	-			
Woight			-	2.0	-	g		
Weight			-	0.07	-	oz.		
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)		
Marking dayion		Case style D ² PAK (TO-263AB)	(TO-263AB) 15ETH06S					
Marking device		Case style TO-262AA						

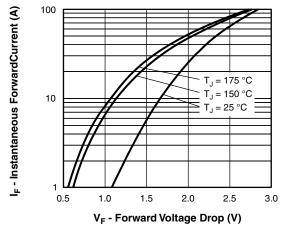


Fig. 1 - Typical Forward Voltage Drop Characteristics

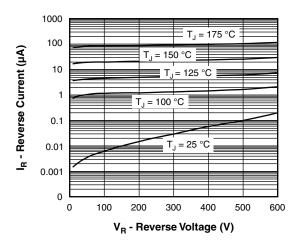


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

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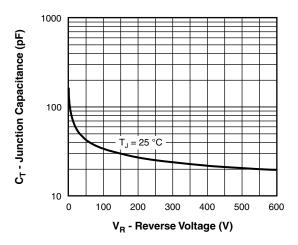


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

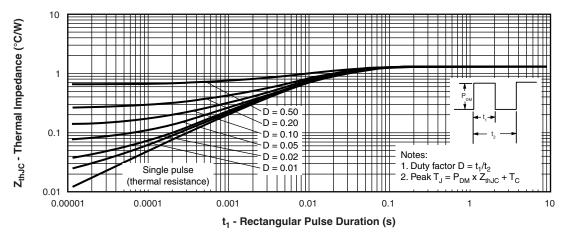


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

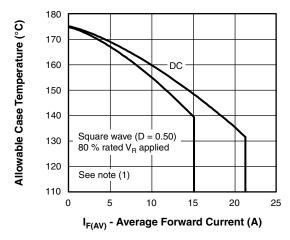


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

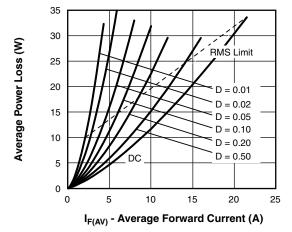


Fig. 6 - Forward Power Loss Characteristics

Note

Formula used: T_C = T_J - (Pd + Pd_{REV}) x R_{th,JC}; Pd = forward power loss = I_{F(AV)} x V_{FM} at (I_{F(AV)}/D) (see fig. 6); Pd_{REV} = inverse power loss = V_{R1} x I_R (1 - D); I_R at V_{R1} = rated V_R



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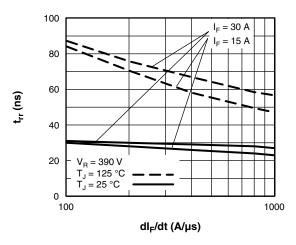


Fig. 7 - Typical Reverse Recovery vs. dl_F/dt

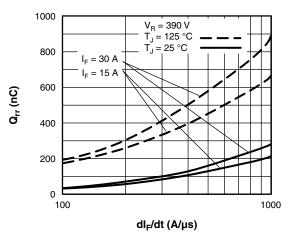
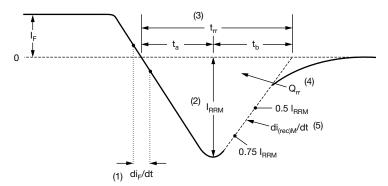


Fig. 8 - Typical Stored Charge vs. dl_F/dt



- (1) di_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) t_{rr} reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RBM} and 0.50 I_{RBM} extrapolated to zero current.
- (4) $\mathbf{Q}_{\rm rr}$ area under curve defined by $\mathbf{t}_{\rm rr}$ and $\mathbf{I}_{\rm RRM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) di_{(rec)M}/dt - peak rate of change of current during t_b portion of t_{rr}

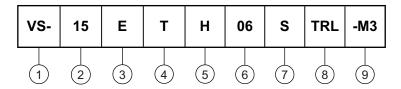
Fig. 9 - Reverse Recovery Waveform and Definitions

VS-15ETH06S-M3, VS-15ETH06-1-M3

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ORDERING INFORMATION TABLE

Device code



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Current rating (15 A)

3 4 5 E = single diode

 $T = TO-220, D^2PAK (TO-263AB)$

H = hyperfast rectifier

Voltage rating (06 = 600 V)

• $S = D^2PAK (TO-263AB)$

• -1 = TO-262AA

8 • None = tube (50 pieces)

• TRL = tape and reel (left oriented, for D²PAK (TO-263AB) package)

• TRR = tape and reel (right oriented, for D²PAK (TO-263AB) package)

9 Environmental digit:

-M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)						
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION				
VS-15ETH06S-M3	50	Antistatic plastic tubes				
VS-15ETH06STRR-M3	800	13" diameter plastic tape and reel				
VS-15ETH06STRL-M3	800	13" diameter plastic tape and reel				
VS-15ETH06-1-M3	50	Antistatic plastic tubes				

LINKS TO RELATED DOCUMENTS						
Dimensions	D ² PAK (TO-263AB)	www.vishay.com/doc?96164				
	TO-262	www.vishay.com/doc?96165				
Part marking information	D ² PAK (TO-263AB)	www.vishay.com/doc?95444				
	TO-262	www.vishay.com/doc?95443				
Packaging information		www.vishay.com/doc?96424				
SPICE model		www.vishay.com/doc?96617				



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D²PAK

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INC	INCHES		OTES SYMBOL MILLIMETERS INCHES	HES	NOTES				
STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOIES		STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190			D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010			E	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039			E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4		е	2.54	BSC	0.100	BSC	
b2	1.14	1.78	0.045	0.070			Н	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4		L	1.78	2.79	0.070	0.110	
С	0.38	0.74	0.015	0.029			L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4		L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065			L3	0.25	BSC	0.010	BSC	
D	8.51	9.65	0.335	0.380	2		L4	4.78	5.28	0.188	0.208	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inches
- (7) Outline conforms to JEDEC® outline TO-263AB

Revision: 13-Jul-17 Document Number: 96164

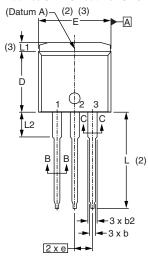


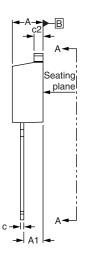
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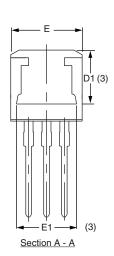
TO-262AA

DIMENSIONS in millimeters and inches

Modified JEDEC® outline TO-262







⊕ 0.010 **M** A**M** B

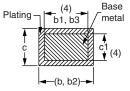
Lead assignments



Diodes 1. - Anode (two die)/open (one die)

2., 4. - Cathode

3. - Anode



Section B - B and C - C Scale: None

SYMBOL	MILLIM	IETERS	INC	INCHES		
	MIN.	MAX.	MIN.	MAX.	NOTES	
Α	4.06	4.83	0.160	0.190		
A1	2.03	3.02	0.080	0.119		
b	0.51	0.99	0.020	0.039		
b1	0.51	0.89	0.020	0.035	4	
b2	1.14	1.78	0.045	0.070		
b3	1.14	1.73	0.045	0.068	4	
С	0.38	0.74	0.015	0.029		
c1	0.38	0.58	0.015	0.023	4	
c2	1.14	1.65	0.045	0.065		
D	8.51	9.65	0.335	0.380	2	
D1	6.86	8.00	0.270	0.315	3	
Е	9.65	10.67	0.380	0.420	2, 3	
E1	7.90	8.80	0.311	0.346	3	
е	2.54	BSC	0.10	0 BSC		
L	13.46	14.10	0.530	0.555		
L1	-	1.65	-	0.065	3	
L2	3.56	3.71	0.140	0.146		

Notes

(4) Dimension b1 and c1 apply to base metal only

Controlling dimension: inches

⁽¹⁾ Dimensioning and tolerancing as per ASME Y14.5M-1994
(2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body

Thermal pad contour optional within dimension E, L1, D1 and E1

Outline conform to JEDEC® TO-262 except A1 (max.), b (min., max.), b1 (min.), b2 (max.), c (min.), c1(min.), c2 (max.), D (min.), E (max.), L1 (max.), L2 (min., max.)



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